IN THE SPECIFICATION:

Please amend the specification as follows:

Please substitute the paragraph beginning at page 1, line 7, with the following.

-- The present invention relates to an anti-vibration apparatus used in an exposure apparatus or the like which mounts positioning equipment such as an optical microscope or X-Y stage and manufactures a device such as a semiconductor device, and to an improvement in an active anti-vibration apparatus which can effectively suppress vibration caused by the motion of the equipment mounted on the anti-vibration apparatus. The present invention also relates to an exposure apparatus and <u>a</u> device manufacturing method using the active anti-vibration apparatus. --

Please substitute the paragraph beginning at page 2, line 7, with the following.

-- Anti-vibration tables are classified into passive anti-vibration tables and active anti-vibration tables. Recently, to meet demands such as high-precision positioning, high-precision scanning, high-speed movement, and the like, for the equipment mounted on the anti-vibration table, an active anti-vibration apparatus tends to be used. An example of an actuator for driving the anti-vibration table includes a pneumatic spring, a voice coil motor, a piezoelectric elements element, and the like. --

Please substitute the paragraph beginning at page 9, line 26, and ending on page 10, line 6, with the following.

-- According to the present invention, the drawback of compensating <u>for</u> the movable load with the pneumatic spring is compensated for by driving with an electromagnetic actuator. For example, even when the moving speed of a movable portion that can move on an anti-vibration table is high, the vibration of the anti-vibration table caused by the movement of the barycenter of the anti-vibration table as a whole can be suppressed. --

Please substitute the paragraph beginning at page 10, line 17, with the following.

-- The electromagnetic actuator applies to the anti-vibration table a force in the same direction as a support direction of said pneumatic spring and/or a direction perpendicular to the above direction. Thus, the drawback of compensating <u>for</u> the movable load with the pneumatic spring can be compensated for by driving with the electromagnetic actuator. --

Please substitute the paragraph beginning at page 11, line 5, with the following.

-- In the active anti-vibration apparatus, at least one of a target position and a target speed of the movable portion is feed-forwarded to the anti-vibration table displacement controller and the anti-vibration table vibration controller. Thus, the rotational moment caused by the movement of the stage can be canceled, and the drawback of compensating <u>for</u> the movable load with the pneumatic spring can be compensated for by driving with the electromagnetic actuator. --

Please substitute the paragraph beginning at page 17, line 12, with the following.

-- In step 1 (design circuit), a semiconductor device circuit is designed. In step 2 (form mask), a mask is formed on the basis of the designed circuit pattern. In step 3 (manufacture wafer), a wafer is manufactured by using a material such as silicon. In step 14 4 (wafer process), called a pre-process, an actual circuit is formed on the wafer by lithography using the prepared mask and wafer. --

Please substitute the paragraph beginning at page 17, line 19, with the following.

-- In step Step 5 (assembly), called a post-process, is the step of forming a semiconductor chip by using the wafer manufactured in step 4, and includes processes such as an assembly process (dicing and bonding) and a packaging process (chip encapsulation). In step 6 (inspection), inspections such as the operation confirmation test and durability test of the semiconductor device manufactured in step 5 are conducted. After these steps, the semiconductor device is completed and shipped, in step 7. --

Please substitute the paragraph beginning at page 18, line 27, and ending on page 19, line 4, with the following.

-- The present invention is not limited tot he above embodiments and various changes and modifications can be made within the spirit and scope of the present invention. Therefore, to appraise apprise the public of the scope of the present invention, the following claims are made. --